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(12) **United States Design Patent**
Min et al.

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(54) **PORTION OF SUBSTRATE FOR LED PACKAGE**

(75) Inventors: **Bong Kul Min**, Seoul (KR); **Gyu Hyeong Bak**, Seoul (KR)

(73) Assignee: **LG Innotek Co., Ltd.**, Seoul (KR)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180; D26/1, 2; 257/79, 80, 257/81, 88, 89, 95, 98, 99, 100, E33.058; 313/483, 498, 500; 362/555, 800
See application file for complete search history.

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Primary Examiner — Selina Sikder

(74) *Attorney, Agent, or Firm* — Birch, Stewart, Kolasch & Birch, LLP

(57) **CLAIM**

The ornamental design for a portion of substrate for LED package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of the portion of substrate for LED package showing our new design;

FIG. **2** is a front view thereof, the rear view being a mirror image thereof;

FIG. **3** is a left side view thereof, the right side view being a mirror image thereof;

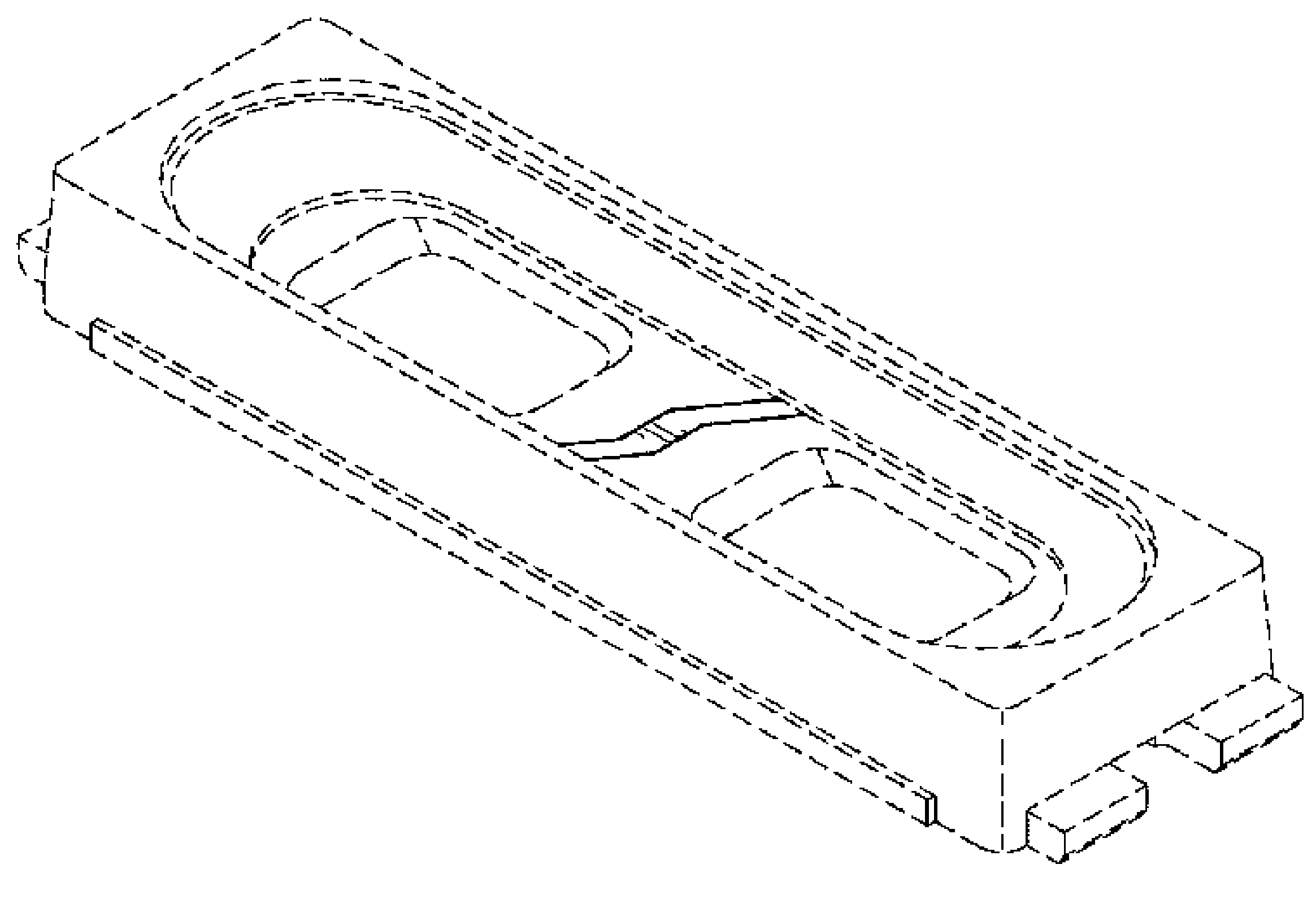
FIG. **4** is a top plan view thereof;

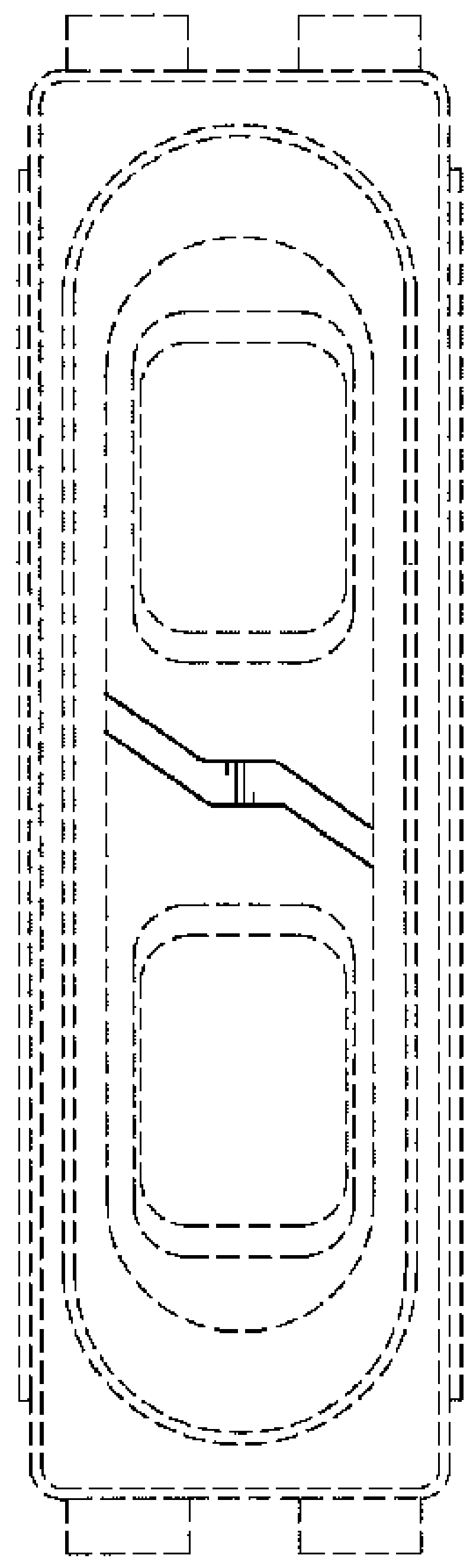
FIG. **5** is a bottom plan view thereof; and,

FIG. **6** is a cross-sectional reference view thereof through VI-VI of FIG. **2**.

The broken lines shown are included for the purpose of illustrating the unclaimed portions of the article and form no part of the claim.

1 Claim, 3 Drawing Sheets





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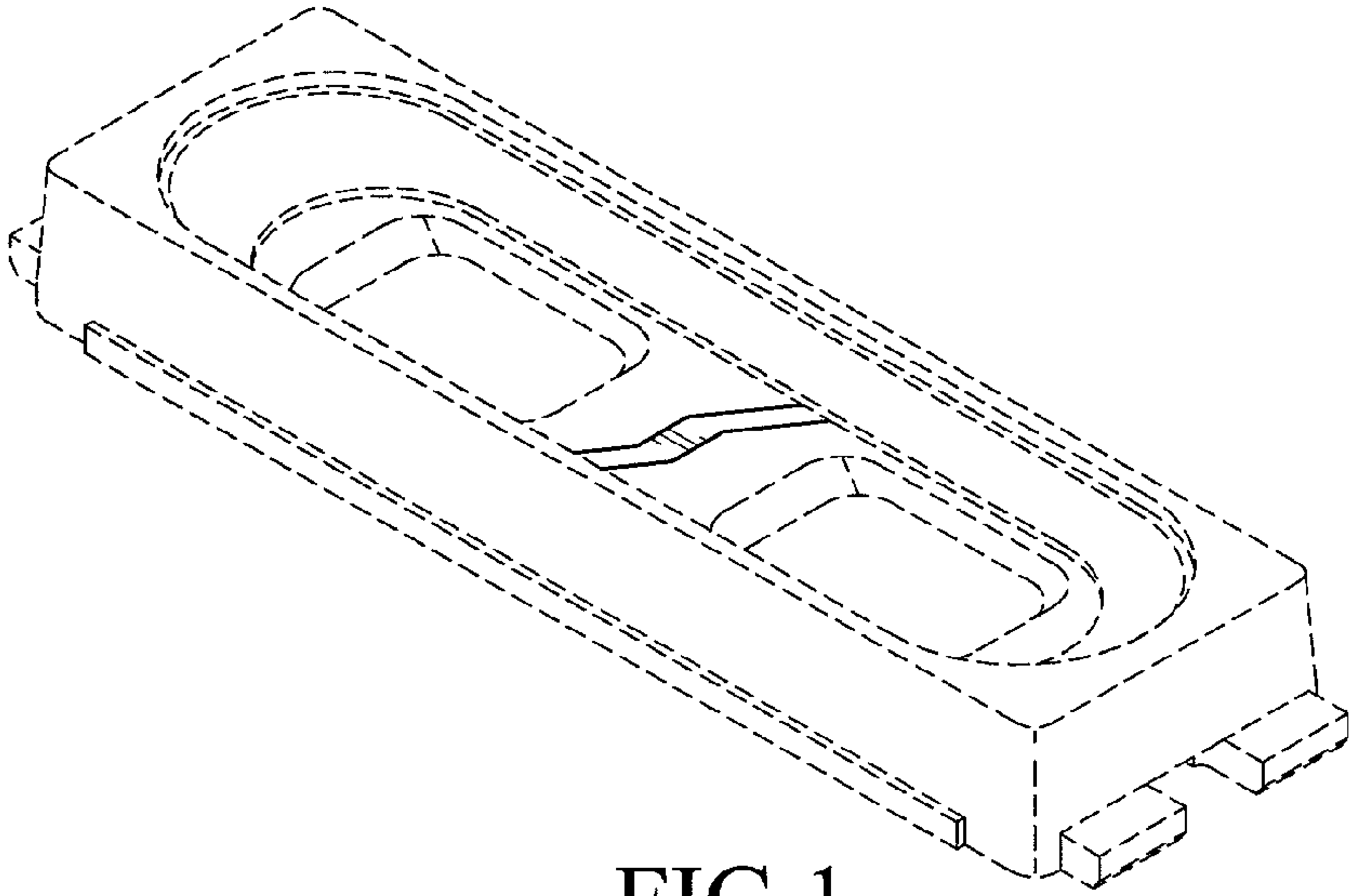

FIG.1

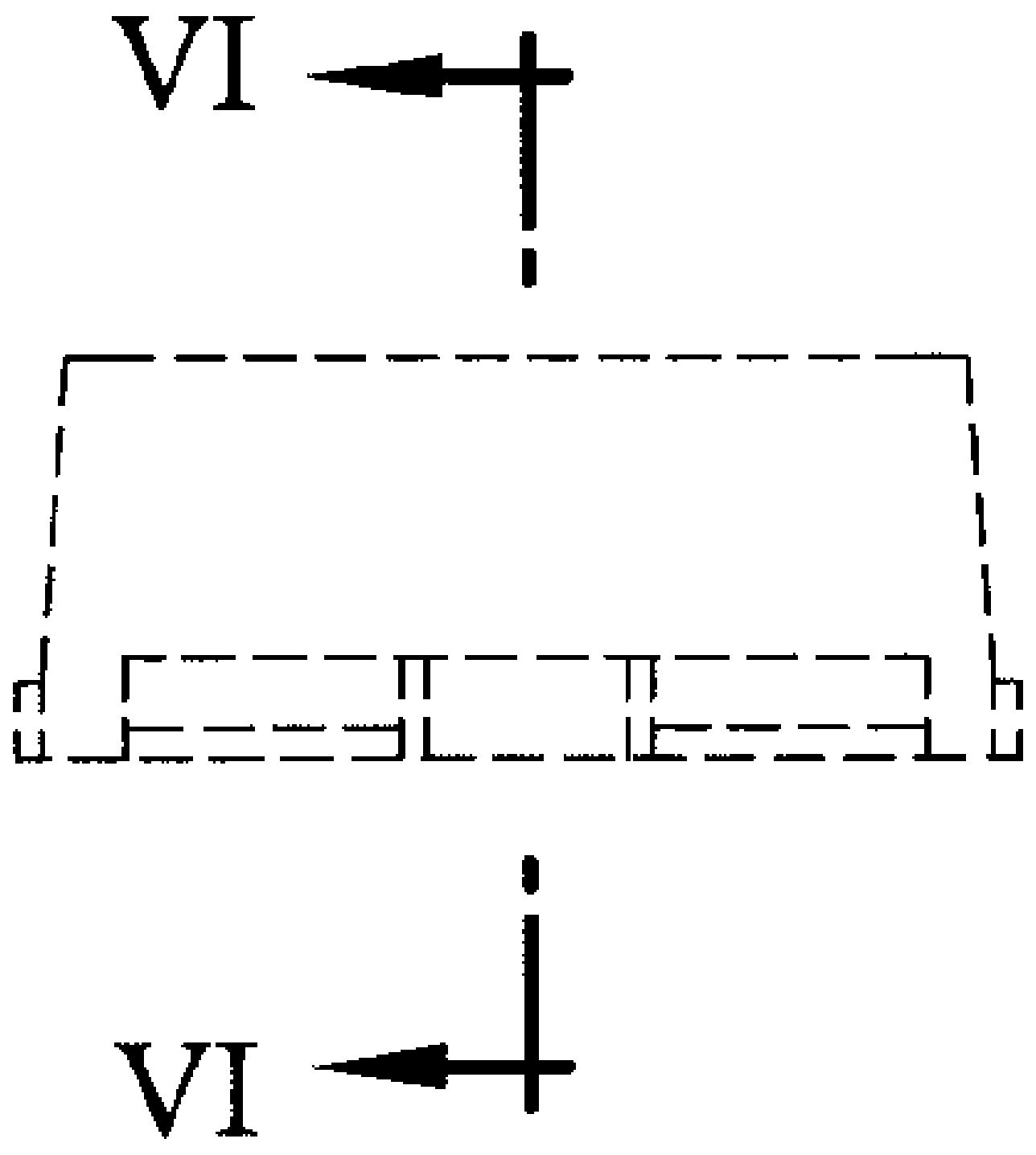

FIG.2

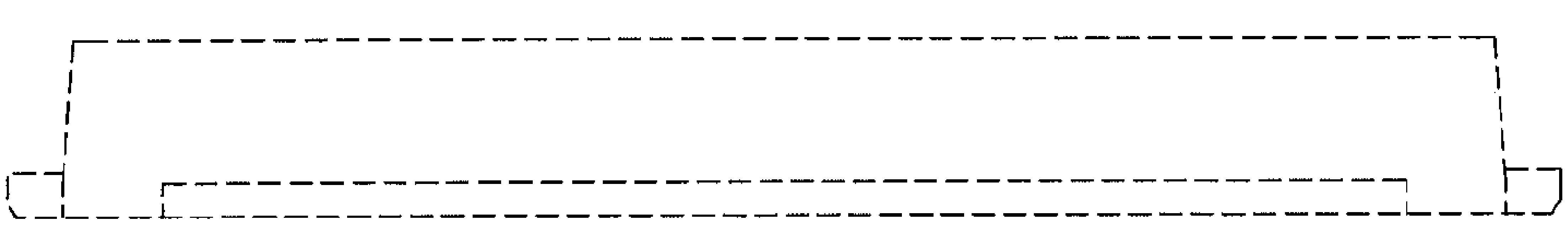

FIG.3

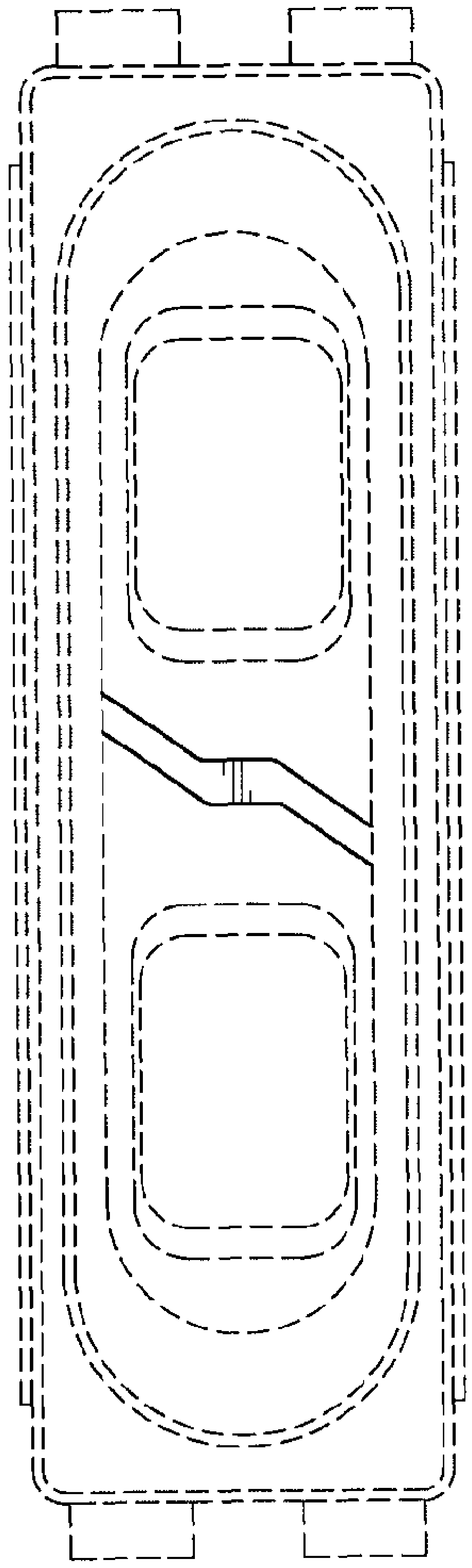

FIG.4

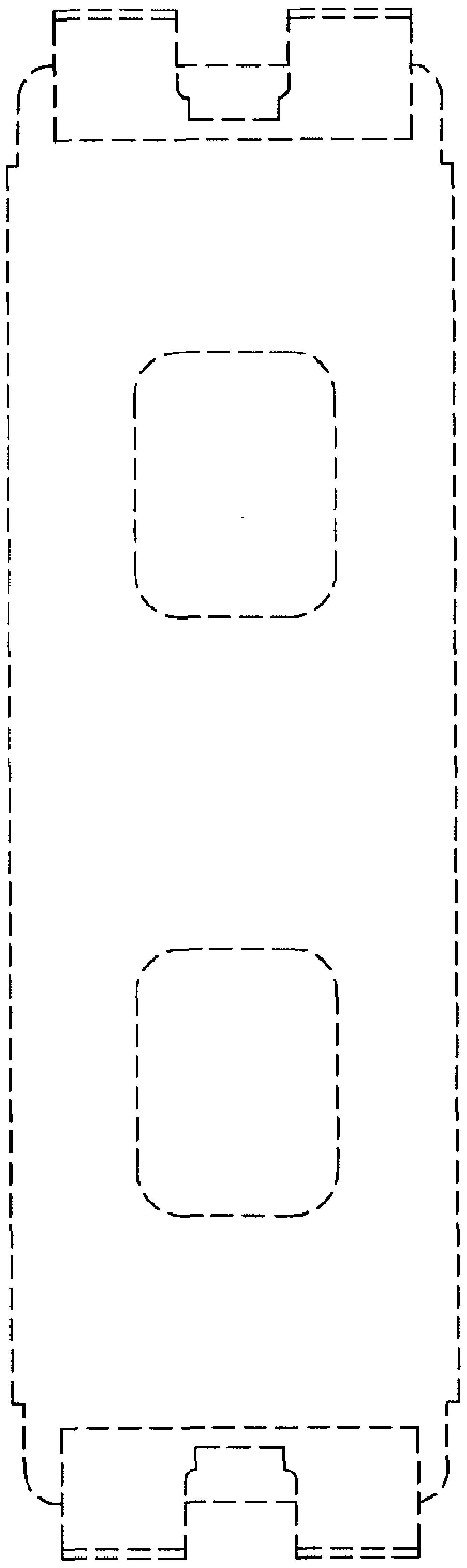

FIG.5

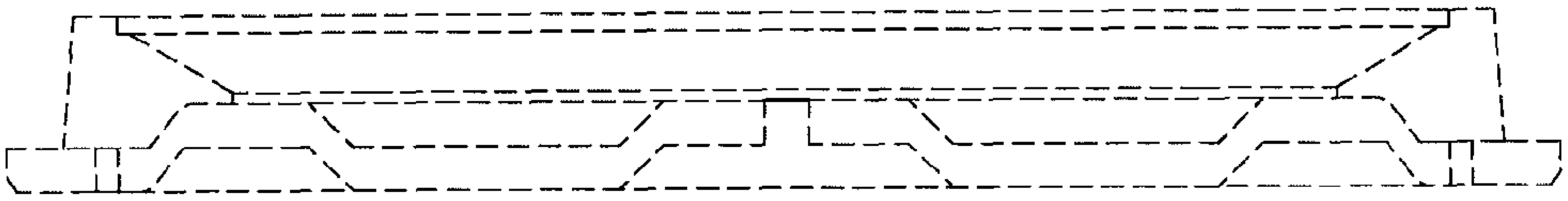

FIG.6